

## Amendments to the Claims

### Claim Listing

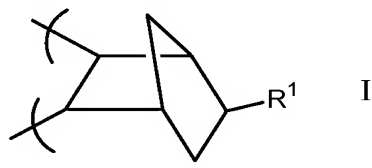
This claim listing replaces all previous versions and prior listings of the claims

1. **(Currently Amended)** A composition comprising:  
a polymer with a glass transition temperature greater than ~~250~~310°C and a water absorption of 2% or less;

one or more metals or metal compounds; and

an organic solvent;

wherein said polymer is a polynorbornene comprising molecular units of formula I



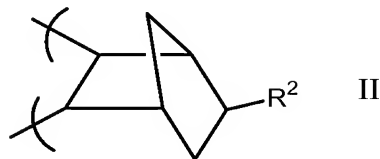
wherein R<sup>1</sup> is independently selected from hydrogen and a (C<sub>1</sub>-C<sub>10</sub>) alkyl.

2. – 4. **(Cancelled)**

5. **(Original)** The composition of claim 1 wherein the water absorption is 1% or less.

6. - .7 **(Cancelled)**

8. **(Currently Amended)** The composition of claim 7 1 wherein the polymer is a polynorbornene that further comprises molecular units of formula II



wherein R<sup>2</sup> is a pendant group capable of participating in a cross-linking or network-forming reaction selected from the group consisting of ~~comprising~~: epoxides, alcohols, silyl ethers, carboxylic acids, esters, and anhydrides; and the molar ratio of molecular units of formula II to formula I is greater than 0 to about 0.4.

9. **(Cancelled)**

10. **(Original)** The composition of claim 1 wherein the polymer contains sites that can crosslink with one or more crosslinking agents.

11. **(Original)** The composition of claim 8 further comprising one or more crosslinking agents which includes polyhydroxystyrene.

12. **(Original)** The composition of claim 1 further comprising a metal adhesion promoter.

13. **(Original)** The composition of claim 12 wherein the metal adhesion promoter is selected from the group consisting of a phenoxy resin, polyhydroxyphenyl ether and 2-mercaptobenzimidazole.

14. **(Original)** The composition of claim 10 further comprising a hydroxyl-capping agent.

15. **(Original)** The composition of claim 14 wherein the hydroxyl-capping agent is a blocked isocyanate agent.

16. **(Currently Amended)** The composition of claim 1 wherein the composition is used to make an electronic component selected from the group consisting of resistors and discrete or planar capacitors.

17. **(Currently amended)** The composition of claim 16 wherein the electronic component is a resistor with a percent resistance change of less than  $\pm 5\%$  with respect to the relative humidity test.

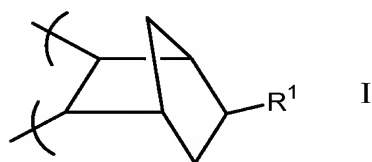
18. **(Currently amended)** The composition of claim 17 wherein the resistor exhibits a percent resistance change of less than  $\pm 1\%$  with respect to an electrostatic discharge ESD test.

19. **(Currently amended)** The composition of claim 16 wherein the electronic component is a discrete or planar capacitor with a capacitance percent loss of less than 5%.

20. **(Original)** The composition of claim 1 wherein the composition is used to prepare a conductive adhesive.

21. **(Original)** The composition of claim 1 wherein the composition has a cure temperature of less than 180°C or can be cured at a peak temperature up to about 270°C with a short infrared cure.

22. **(Currently amended)** A composition comprising a polymer with a glass transition temperature greater than ~~250~~310°C and a water absorption of 2% or less, and an organic solvent wherein said polymer is a polynorbornene comprising molecular units of formula I

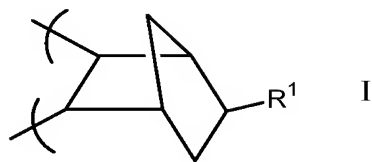


wherein R<sup>1</sup> is independently selected from hydrogen and a (C<sub>1</sub>-C<sub>10</sub>) alkyl.

23. **(Cancelled)**

24. **(Original)** The composition of claim 22 wherein the composition has a cure temperature of less than 180°C or can be cured at a peak temperature up to about 270°C with a short infrared cure, and the composition is used as an encapsulant or an integrated circuit and wafer-level package selected from semiconductor stress buffers, interconnect dielectrics, protective overcoats bond pad redistribution, or solder bump underfills.

25. **(Currently Amended)** A method of making a PTF resistor comprising:  
combining a polymer with a glass transition temperature greater than ~~250~~310°C and a water absorption of less than 2%, one or metals or metal compounds, and an organic solvent to provide a PTF resistor composition;  
applying the PTF resistor composition to a substrate; and  
curing the applied PTF resistor composition; and  
wherein the polymer is a polynorbornene comprising molecular units of formula I



wherein R<sup>1</sup> is independently selected from hydrogen and a (C<sub>1</sub>-C<sub>10</sub>)alkyl.

26. **(Cancelled)**

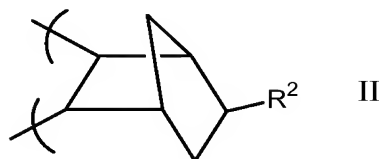
27. **(Original)** The method of claim 25 wherein the curing of the applied PTF resistor composition includes a cure temperature of less than 180°C or a peak temperature up to about 270°C with a short infrared cure.

28. **(Cancelled)**

29. **(Original)** The method of claim 25 wherein the polymer has a water absorption of 1% or less.

30. **(Cancelled)**

31. **(Currently Amended)** The method of claim ~~30~~25 wherein the polymer is a polynorbornene that further comprises molecular units of formula II



wherein R<sup>2</sup> is a crosslinkable epoxy group, and the molar ratio of molecular units of formula II to formula I is greater than 0 to about 0.4.

32. **(Cancelled)** ~~The method of claim 26 wherein the polymer is a polyarylate.~~

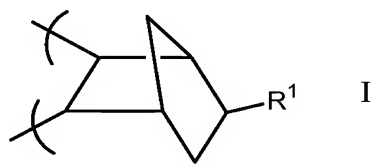
33. **(Currently Amended)** An electronic component selected from the group consisting of PTF resistors and discrete or planar resistors, wherein the electronic component comprises a cured composition prepared by a process comprising:

combining a polymer with a glass transition temperature greater than ~~250~~310°C and a water absorption of 2% or less, one or metals or metal compounds, and an organic solvent to provide an uncured composition;

applying the uncured composition to a substrate; and

curing the applied composition; and

wherein the polymer is a polynorbornene comprising molecular units of formula I



wherein R<sup>1</sup> is independently selected from hydrogen and a (C<sub>1</sub>-C<sub>10</sub>)alkyl.